

Abstract of the Disclosure

Provided are a mold die for molding a chip array, molding equipment including such a mold die and a molding method utilizing such molding equipment. The mold die provides for the selective injection of mold resin through a corner gate controlled by a gate block whereby the flow of the mold resin is neither perpendicular nor parallel to the side surfaces of the semiconductor chips arranged in the chip array. In this manner failures associated with the sweeping effects of the mold resin flowing past the bonding wires on the semiconductor chips may be reduced.